IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of:

Shunpei YAMAZAKI et al

Serial No.: Not Assigned

Filed: Herewith

Art Unit:

For: SEMICONDUCTOR DEVICE AND

MANUFACTURING METHOD THEREOF

"Express Mail" Mailing Label No. EV 321710865
Date of Deposit September 19, 2003

I hereby certify that this correspondence is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR1.10 on the date indicated above and is addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450

Name: Yue p Ruan (typed or priviled)

) Signature You &

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

Pursuant to 37 C.F.R. §1.97, as revised on February 4, 1992, 1135 OG 23-24, Applicant hereby calls the Examiner's attention to documents listed on the attached form, which documents may be material to the examination of this application. A copy of each of the references was submitted to the Patent Office or was cited by the Examiner in the parent application, Serial No. 09/619,732, filed July 19, 2000, which is being relied upon for an earlier filing date under 35 U.S.C. 120 (37 C.F.R. §1.98(d)).

No inference should be drawn that the attached list sets forth a comprehensive investigation of the prior art, that any or all are pertinent to the invention, or that any apparatus disclosed is equivalent to the subject invention.

The citation of the above-discussed documents is not to be construed as an assertion that more pertinent art could not possibly be in existence. Citation of any document herein is not to be construed as an admission that any subject matter disclosed in the document is necessarily within the inventive field of endeavor, that any disclosure is necessarily prior in time to a particular date which may be relevant to the instant patent application, and/or that any disclosure is otherwise necessarily prior art with respect to the instant invention.

Applicant also respectfully reserves the right to later set forth how the instant invention is distinguished over the disclosure of any document or other art, including the disclosure of those documents discussed herein, that may be cited by the Examiner in rejecting a claim in the instant patent application.

A first office action, notice of allowance or issue fee notification has not been received in this case, so applicant does not believe that a fee is due. However, if any such fee is required, please charge our Deposit Account No. 50/1039.

Respectfully submitted,

Mark J. Marphy

Registration No: 34,225

COOK, ALEX, McFARRON, MANZO, CUMMINGS & MEHLER, LTD. 200 West Adams Street Suite 2850 Chicago, Illinois 60606 (312) 236-8500

LIST OF PUBLICATIONS CITED BY APPLICANT			<u>Atty. Docket No.</u> 0553-0200.01		<u>Serial No.</u> Not Assigned		
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*EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP form. Draw line through citation if not in conformance and not considered Include a copy of this form with the next communication to applicant.